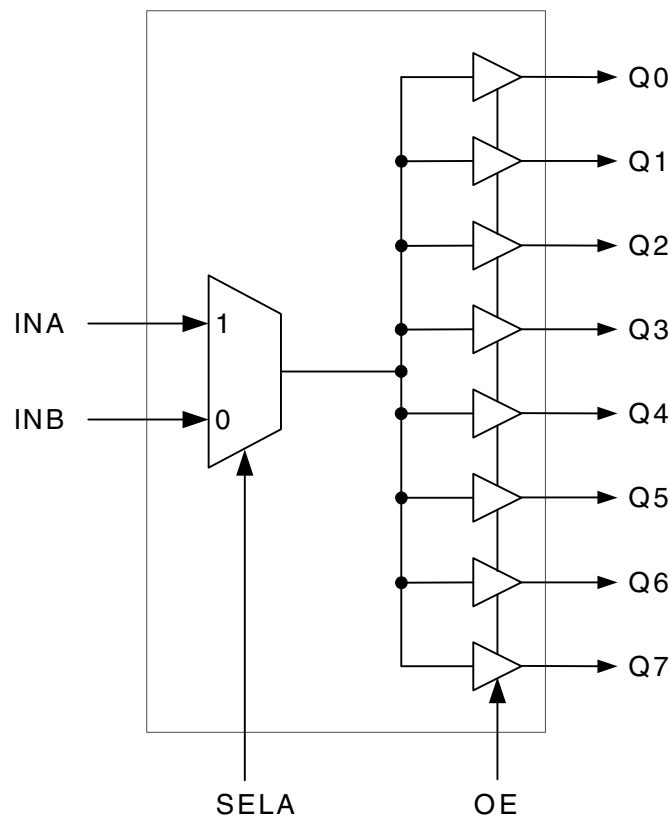## Description

The 552-02S is a low skew, single-input to eight- output clock buffer. The device offers a dual input with pin select for switching between two clock sources. It has best in class Additive Phase Jitter of sub 50fsec

IDT makes many non-PLL and PLL based low skew output devices as well as Zero Delay Buffers to synchronize clocks. Contact us for all of your clocking needs.

Features

- Low RMS Additive Phase Jitter: 50fs
- Low output skew: 50ps
- Operating Voltages of 1.8V to 3.3V
- Packaged in 16-pin TSSOP and 16-pin VFQFN, Pb-free
- Input clock multiplexer simplifies clock selection
- Output Enable pin tri-states outputs
- Input/Output clock frequency up to 200 MHz
- Low power CMOS technology
- 3.3V tolerant inputs
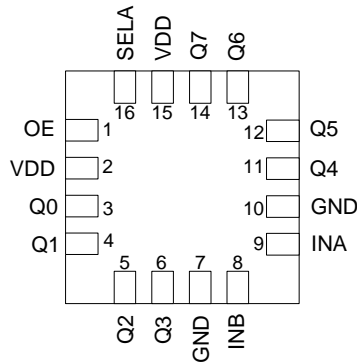- Extended temperature (-40°C to +105°C)

Block Diagram

Pin Assignments
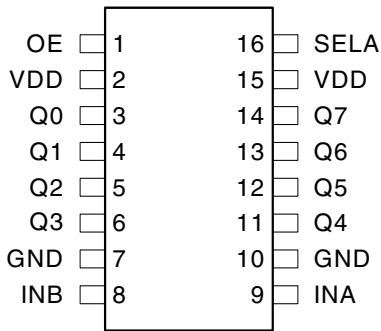
16 Pin TSSOP

16-pin VFQFN

Input Source Select

SELA	Input
0	INB
1	INA

Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	OE	Input	Output Enable. Tri-states outputs when low. Internal pull-up resistor.
2	VDD	Power	Connect to +1.8V, +2.5V or +3.3V. Must be the same as pin 15.
3	Q0	Output	Clock Output 0.
4	Q1	Output	Clock Output 1.
5	Q2	Output	Clock Output 2.
6	Q3	Output	Clock Output 3.
7	GND	Power	Connect to ground.
8	INB	Input	Clock Input B. 3.3V tolerant.
9	INA	Input	Clock Input A. 3.3V tolerant.
10	GND	Power	Connect to ground.
11	Q4	Output	Clock Output 4.
12	Q5	Output	Clock Output 5.
13	Q6	Output	Clock Output 6.
14	Q7	Output	Clock Output 7.
15	VDD	Power	Connect to +1.8V, +2.5V or +3.3V. Must be the same as pin 2.
16	SELA	Input	Selects either INA or INB. Internal pull-up resistor.

External Components

A minimum number of external components are required for proper operation. Decoupling capacitors of 0.01 μF should be connected between VDD on pin 2 and GND on pin 7, and between VDD on pin 15 and GND on pin 10, as close to the device as possible. A 33 Ω series terminating resistor should be used on each clock output if the trace is longer than 1 inch.

To achieve the low output skews that the 552-02S is capable of, careful attention must be paid to board layout. Essentially, all 8 outputs must have identical terminations, identical loads, and identical trace geometries. If they do not, the output skew will be degraded. For example, using a 30Ω series termination on one output (with 33Ω on the others) will cause at least 15ps of skew.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 552-02S. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	3.465V
All Inputs and Outputs	-0.5 V to 3.465V
Ambient Operating Temperature, Extended	-40 to +105°C
Storage Temperature	-65 to +150 °C
Junction Temperature	175 °C
Soldering Temperature	260 °C

Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature, Extended	-40	–	+105	°C
Power Supply Voltage (measured in respect to GND)	+1.71		+3.465	V

DC Electrical Characteristics

VDD=1.8 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		1.71		1.89	V
Input High Voltage, INA, INB	V_{IH}	Note 1	0.7xVDD		1.89	V
Input Low Voltage, INA, INB	V_{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V_{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V_{IL}				0.3xVDD	V
Output High Voltage	V_{OH}	I_{OH} = -10 mA	1.3			V
Output Low Voltage	V_{OL}	I_{OL} = 10 mA			0.35	V
Operating Supply Current	IDD	No load, 135 MHz		32		mA

VDD=2.5 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		2.375		2.625	V
Input High Voltage, INA, INB	V_{IH}	Note 1	0.7xVDD		2.625	V
Input Low Voltage, INA, INB	V_{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V_{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V_{IL}				0.3xVDD	V
Output High Voltage	V_{OH}	I_{OH} = -16 mA	1.8			V
Output Low Voltage	V_{OL}	I_{OL} = 16 mA			0.5	V
Operating Supply Current	IDD	No load, 135 MHz		43		mA

VDD=3.3 V ±5%, Ambient temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		3.135		3.465	V
Input High Voltage, INA, INB	V_{IH}	Note 1	0.7xVDD		3.465	V
Input Low Voltage, INA, INB	V_{IL}	Note 1			0.3xVDD	V
Input High Voltage, OE, SELA	V_{IH}		0.7xVDD		VDD	V
Input Low Voltage, OE, SELA	V_{IL}				0.3xVDD	V
Output High Voltage	V_{OH}	I_{OH} = -25 mA	2.2			V
Output Low Voltage	V_{OL}	I_{OH} = 25 mA			0.7	V
Operating Supply Current	IDD	No load, 135 MHz		55		mA

AC Electrical Characteristics

VDD = 1.8V ±5%, Ambient Temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t_{OR}	0.36 to 1.44 V, C_L=5 pF		1	1.5	ns
Output Fall Time	t_{OF}	1.44 to 0.36 V, C_L=5 pF		1	1.5	ns
Start-up Time	$t_{START-UP}$	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.5	3	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

VDD = 2.5V ±5%, Ambient Temperature -40°C to +105°C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t_{OR}	0.5 to 2.0 V, C_L=5 pF		0.6	1.0	ns
Output Fall Time	t_{OF}	2.0 to 0.5 V, C_L=5 pF		0.6	1.0	ns
Start-up Time	$t_{START-UP}$	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.7	3.5	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

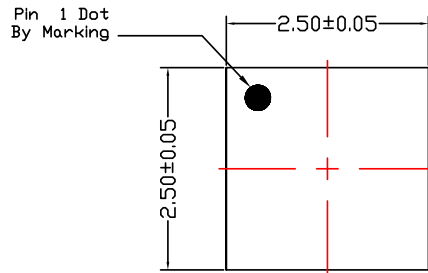**VDD = 3.3V ±5%**, Ambient Temperature -40°C to +105°C, unless stated otherwise

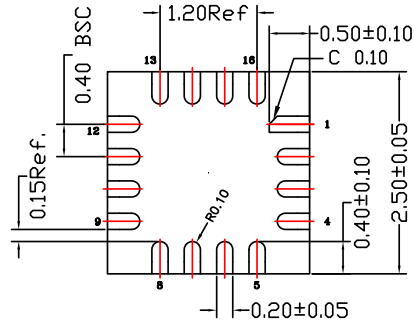| Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Frequency			0		200	MHz
Output Rise Time	t_{OR}	0.66 to 2.64 V, C_L=5 pF		0.6	1.0	ns
Output Fall Time	t_{OF}	2.64 to 0.66 V, C_L=5 pF		0.6	1.0	ns
Start-up Time	$t_{START-UP}$	Part start-up time for valid outputs after VDD ramp-up			2	ms
Propagation Delay	Note 1	135MHz	2	2.5	3	ns
Buffer Additive Phase Jitter, RMS		125MHz, Integration Range: 12KHz-20MHz		50	65	ps
Output to output skew	Note 2	Rising edges at VDD/2		0	65	ps
Input A to Input B skew	Note 3			0	50	ps

Notes:
1. With rail-to-rail input clock.
2. Between any two outputs with equal loading.
3. Propagation delay matching through the part.
4. Duty cycle on outputs will match incoming clock duty cycle. Consult IDT for tight duty cycle clock generators.

REVISIONS

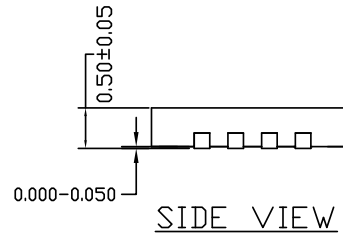| REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	04/03/14	JH
01	ADD PIN1 CHAMFER	12/11/14	JH

Pin 1 Dot
By Marking

2.50±0.05

2.50±0.05

TOP VIEW

1.20Ref
0.40 BSC
0.50±0.10
C 0.10
0.15Ref.
13
16
12
1
R0.10
9
4
0.40±0.10
2.50±0.05
8
5
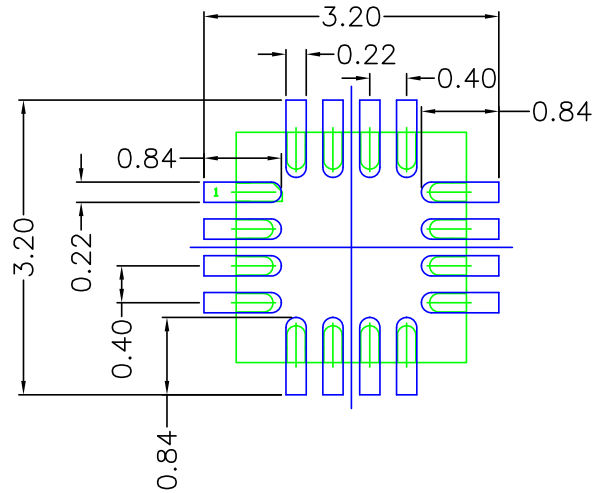0.20±0.05

BOTTOM VIEW

0.50±0.05

0.000-0.050

SIDE VIEW

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982

2. ALL DIMENSIONS ARE IN MILLIMETERS.

TOLERANCES UNLESS SPECIFIED	
DECIMAL	ANGULAR
X±	±1°
XX±	
XXX±	

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San Jose CA 95138
PHONE: (408) 284-8200
FAX: (408) 284-8591

APPROVALS	DATE	TITLE CMG 16 PACKAGE OUTLINE
DRAWN JH	04/03/14	2.5 x 2.5 mm BODY
CHECKED		0.40 mm PITCH VFQFN

SIZE	DRAWING No.	REV
C	PSC-4478	01

DO NOT SCALE DRAWING | SHEET 1 OF 2

Package Outline and Dimensions, cont. (16-pin VFQFN)

APRIL 18, 2017

7

LOW SKEW 2-INPUT MUX AND 1 TO 8 CLOCK BUFFER

RECOMMENDED LAND PATTERN DIMENSION

NOTES:
1. ALL DIMENSIONS ARE IN MM. ANGLES IN DEGREES.
2. TOP DOWN VIEW AS VIEWED ON PCB.
3. COMPONENT OUTLINE IS SHOWN FOR REFERENCE IN GREEN.
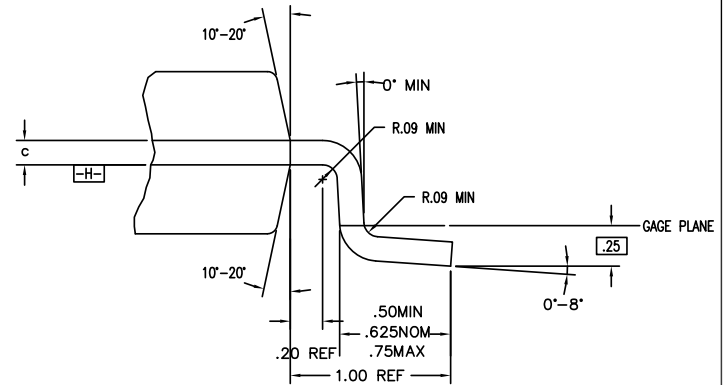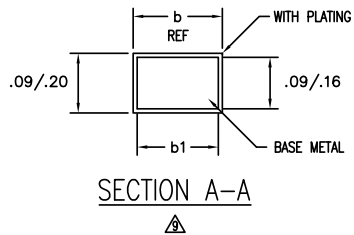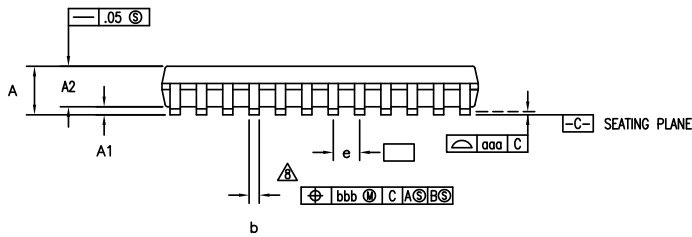4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT
   FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED		IDT™ www.IDT.com	6024 Silver Creek Valley Road San Jose CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-8591
DECIMAL	ANGULAR		
X±	±1°		
XX±			
XXX±			

APPROVALS	DATE	TITLE CMG 16 PACKAGE OUTLINE		
DRAWN ƎH	04/03/14	2.5 x 2.5 mm BODY		
CHECKED		0.40 mm PITCH VFQFN		
		SIZE C	DRAWING No. PSC-4478	REV 01
		DO NOT SCALE DRAWING		SHEET 2 OF 2

DATE CREATED	REV	REVISIONS	AUTHOR
		DESCRIPTION	
08/25/98	02	ADD 14 & 16 LD	T. VU
07/10/99	03	ADD 8 LD	T. VU
5/23/01	04	ADDED TOPMARK TO TITLE	
10/14/04	05	ADD "GREEN" PGG NOMENCLATURE	TU VU
3/8/13	06	ADDED PACKAGE CODE	RAC
9/3/14	07	ADD TOLERANCE FOR A, A1, E AND b	CK LEE
3/10/17	08	ADD OPTION T1	R.TANH

NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

DETAIL B

SECTION A-A

SEE DETAIL B

INDEX AREA
(E1/2 X D/2)

N/2 TIPS

SEATING PLANE

WITH PLATING
REF
.09/.20
.09/.16
BASE METAL

10°-20°
0° MIN
R.09 MIN
R.09 MIN
GAGE PLANE
.25
0°-8°
.50MIN
.625NOM
.75MAX
.20 REF
1.00 REF

TOLERANCES
UNLESS SPECIFIED
DECIMAL   ANGULAR
XX±   ±
XXX±
XXXX±

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www.IDT.com

TITLE PG/PGG PACKAGE OUTLINE
(PG OR PA TOPMARK CODE)
4.4 mm BODY WIDTH TSSOP .65 mm PITCH

SIZE	DRAWING No.	REV
C	PSC-4056	08

DO NOT SCALE DRAWING   SHEET 1 OF 3

DATE CREATED	REV	REVISIONS DESCRIPTION	AUTHOR
08/25/98	02	ADD 14 & 16 LD	T. VU
07/10/99	03	ADD 8 LD	T. VU
5/23/01	04	ADDED TOPMARK TO TITLE	
10/14/04	05	ADD "GREEN" PGG NOMENCLATURE	TU VU
3/8/13	06	ADDED PACKAGE CODE	RAC
9/3/14	07	ADD TOLERANCE FOR A, A1, E AND b	CK LEE
3/10/17	08	ADD OPTION T1	R.TANH

NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

SYMBOL	PG/PGG8 JEDEC VARIATION AA MIN	NOM	MAX	NOTE	PG/PGG14 JEDEC VARIATION AB-1 MIN	NOM	MAX	NOTE	PG/PGG16 JEDEC VARIATION AB MIN	NOM	MAX	NOTE	PG/PGG20 JEDEC VARIATION AC MIN	NOM	MAX	NOTE	PG/PGG24 JEDEC VARIATION AD MIN	NOM	MAX	NOTE	PG/PGG28 JEDEC VARIATION AE MIN	NOM	MAX	NOTE
A	.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20		.85	1.10	1.20	
A1	.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15		.05	.10	.15	
A2	.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05		.80	1.00	1.05	
D	2.90	3.00	3.10	4,5	4.90	5.00	5.10	4,5	4.90	5.00	5.10	4,5	6.40	6.50	6.60	4,5	7.70	7.80	7.90	4,5	9.60	9.70	9.80	4,5
E	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3	6.20	6.40	6.60	3
E1	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6	4.30	4.40	4.50	4,6
e	.65 BSC				.65 BSC				.65 BSC				.65 BSC				.65 BSC				.65 BSC			
b	.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30		.19	.25	.30	
b1	.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25		.19	.22	.25	
aaa	–	–	.10		–	–	.10		–	–	.10		–	–	.10		–	–	.10		–	–	.10	
bbb	–	–	.10		–	–	.10		–	–	.10		–	–	.10		–	–	.10		–	–	.10	
N	8				14				16				20				24				28			

NOTES:

1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M–1994

2 DATUMS ⌴-A-⌴ AND ⌴-B-⌴ TO BE DETERMINED AT DATUM PLANE ⌴-H-⌴

3 DIMENSION E TO BE DETERMINED AT SEATING PLANE ⌴-C-⌴

4 DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE ⌴-H-⌴

5 DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE

6 DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE

7 DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED

8 LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT

9 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP

10 ALL DIMENSIONS ARE IN MILLIMETERS

11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO–153, VARIATION AA, AB–1, AB, AC, AD & AE

SYMBOL	OPTION T1 PGG14T1 JEDEC VARIATION AB-1 MIN	NOM	MAX	NOTE
A	.90	1.10	1.20	
A1	.05	.10	.15	
A2	.80	1.00	1.05	
D	4.90	5.00	5.10	4,5
E	6.20	6.40	6.60	3
E1	4.30	4.40	4.50	4,6
e	.65 BSC			
b	.19	.25	.30	
b1	.19	.22	.25	
c	.09	–	.20	
aaa	–	–	.10	
bbb	–	–	.10	
N	14			

TOLERANCES UNLESS SPECIFIED
DECIMAL   ANGULAR
XX±   ±
XXX±
XXXX±

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www.IDT.com

TITLE PG/PGG PACKAGE OUTLINE
(PG OR PA TOPMARK CODE)
4.4 mm BODY WIDTH TSSOP .65 mm PITCH

SIZE	DRAWING No.	REV
C	PSC–4056	08

DO NOT SCALE DRAWING   SHEET 2 OF 3

DATE CREATED	REV	REVISIONS DESCRIPTION	AUTHOR
08/25/98	02	ADD 14 & 16 LD	T. VU
07/10/99	03	ADD 8 LD	T. VU
5/23/01	04	ADDED TOPMARK TO TITLE	
10/14/04	05	ADD "GREEN" PGG NOMENCLATURE	TU VU
3/8/13	06	ADDED PACKAGE CODE	RAC
9/3/14	07	ADD TOLERANCE FOR A, A1, E AND b	CK LEE
3/10/17	08	ADD OPTION T1	R.TANH

NOTE: REFER TO DCP FOR OFFICIAL RELEASE DATE

LAND PATTERN DIMENSIONS

	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
P	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40	7.20	7.40
P1	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40	4.20	4.40
P2	1.95 BSC		3.90 BSC		4.55 BSC		5.85 BSC		7.15 BSC		8.45 BSC	
X	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50	.30	.50
e	.65 BSC		.65 BSC		.65 BSC		.65 BSC		.65 BSC		.65 BSC	
N	8		14		16		20		24		28	

TOLERANCES
UNLESS SPECIFIED
DECIMAL   ANGULAR
XX±   ±
XXX±
XXXX±

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FAX: (408) 492-8674

TITLE   PG/PGG PACKAGE OUTLINE
(PG OR PA TOPMARK CODE)
4.4 mm BODY WIDTH TSSOP .65 mm PITCH

SIZE	DRAWING No.	REV
C	PSC-4056	08

DO NOT SCALE DRAWING   SHEET 3 OF 3

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
552-02SPGGI		Tubes	16-pin TSSOP	-40°C to +105°C
552-02SPGGI8	TBD	Tape and Reel	16-pin TSSOP	-40°C to +105°C
552-02SCMGI		Tubes	16-pin VFQFN	-40°C to +105°C
552-02SCMGI8		Tape and Reel	16-pin VFQFN	-40°C to +105°C

"G" after the two-letter package code denotes Pb-Free configuration, RoHS compliant.

Marking Diagrams

IDT552-0
2SPGGI
YYWW$

● LOT

16-pin TSSOP

02SI
Y**

●

16-pin QFN
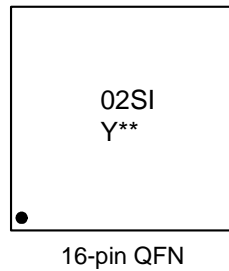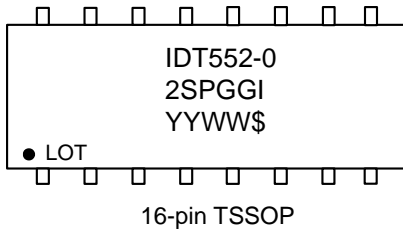
Notes:
1. "**" is the lot sequence.
2. "YYWW" or "Y" is the last digit(s) of the year and week that the part was assembled.
3. "$" denotes the mark code.
4. "LOT" denotes lot number.
5. "G" after the two-letter package code denotes RoHS compliant package.
6. "I" denotes extended temperature range device.
7. Bottom marking: country of origin (TSSOP only).

Revision History

Rev.	Date	Originator	Description of Change
B	04/18/17	C.P.	1. Replaced package outline drawings with latest CMG16 and PGG16 versions. 2. Updated legal disclaimer.
A	07/11/16	H.G.	Release to final.

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